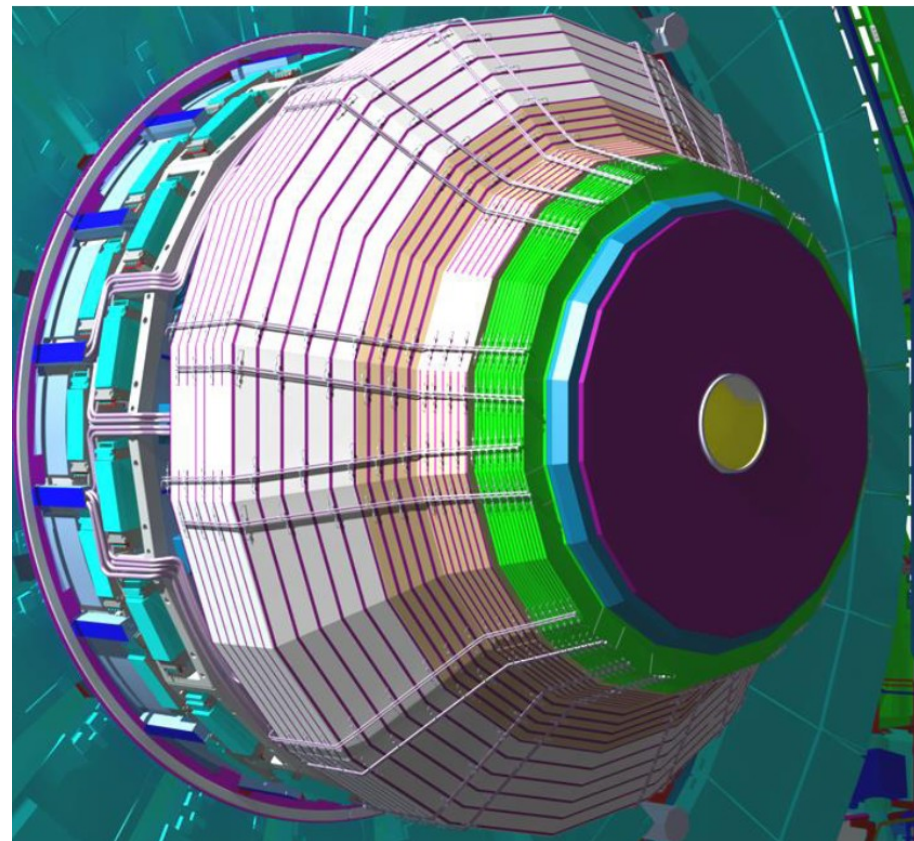


# Electronics and Triggering Challenges for the CMS High-Granularity Calorimeter

M.Noy (CERN)

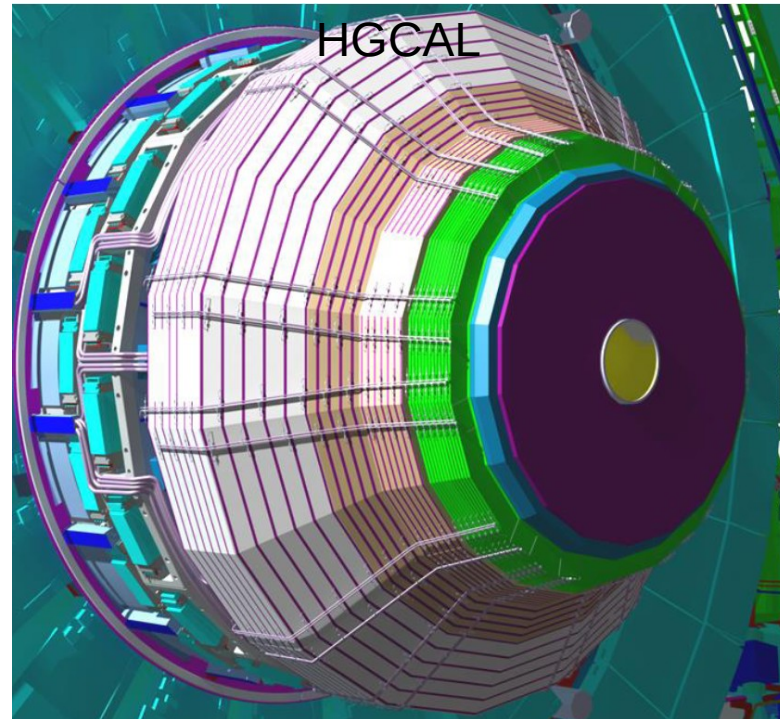
On behalf of the CMS Collaboration

- Brief Overview
  - Structure
  - Requirements
  - Constraints
- Tiling and Variants
- Readout Architecture
  - Data & Trigger Paths
- LD-HexBoard Design
- Power Tree
  - Power Modelling
- Mechanical Mockup
  - Phenomenology & design feasibility studies



# Out with the old, in with the new...

Present CMS EndCap Calorimeters



- Calorimeter Endcap
  - Weight ~ 250 tonnes
  - Sampling calorimeter
  - CE-E(lectromagnetic) and CE-H(adronic)

# Detector Structure and Key Parameters

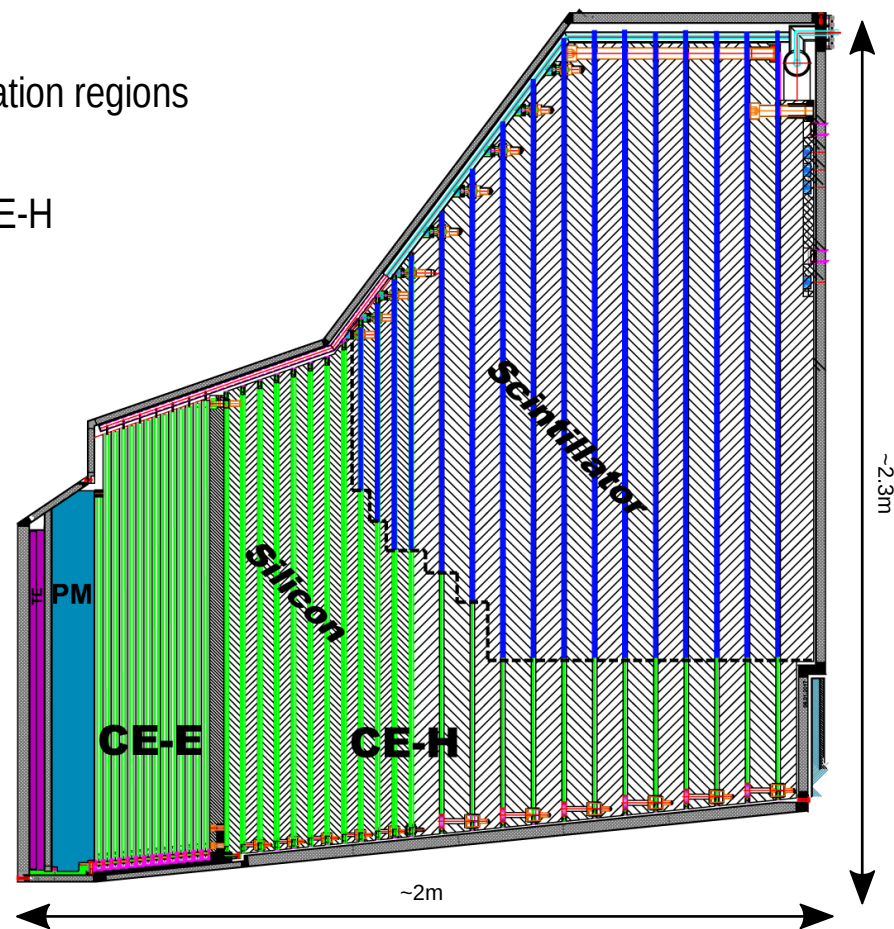


## Active Elements:

- Hexagonal modules based on Si sensors in CE-E and high-radiation regions of CE-H
- Scintillating tiles with SiPM readout in low-radiation regions of CE-H

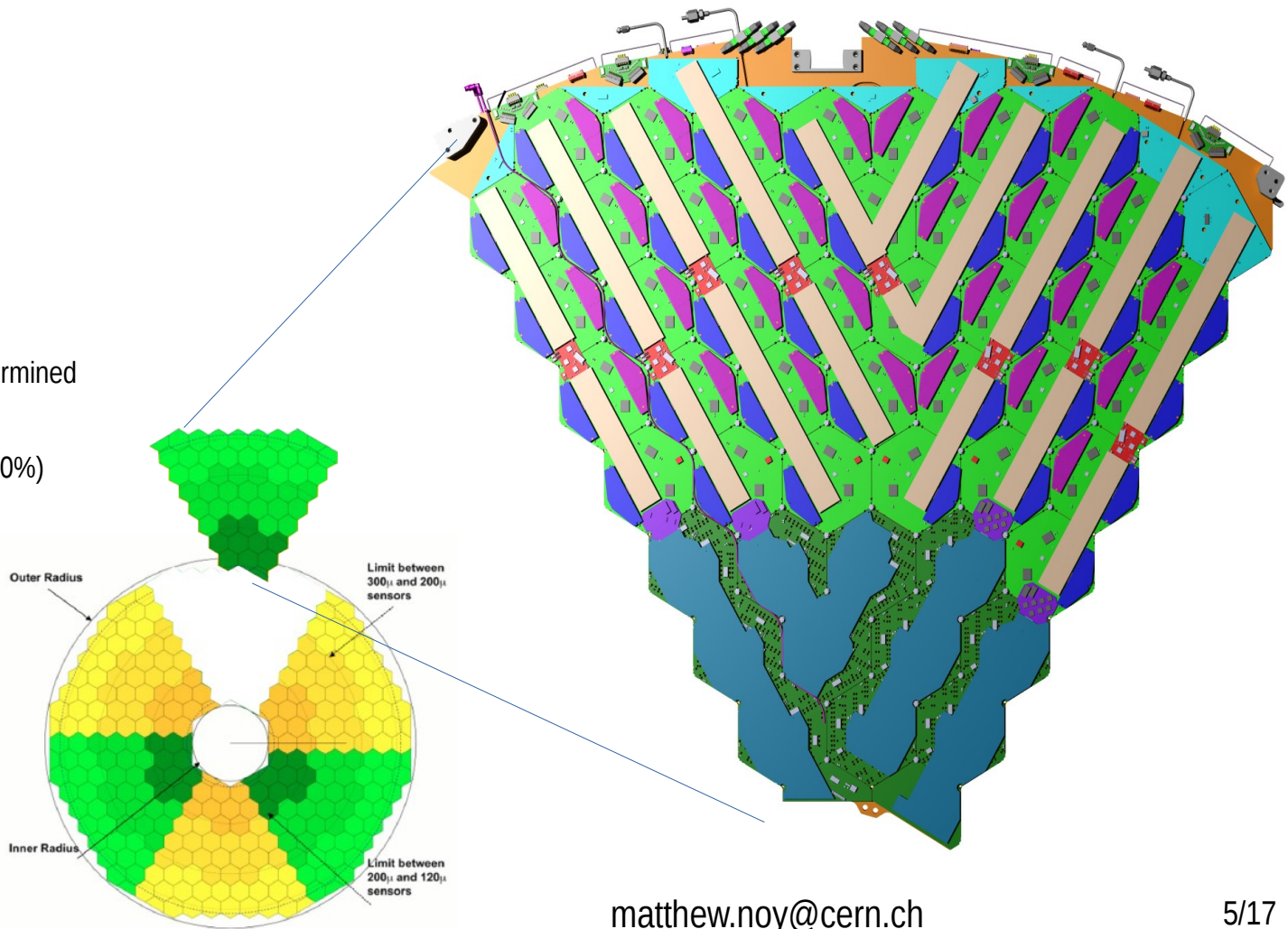
## Key Parameters:

- HGCal covers  $1.5 < \eta < 3.0$
- Up to 200 Mrads ;  $8 \times 10^{15}$  n/cm<sup>2</sup>
- Full system maintained at -30 °C
- ~400 m<sup>2</sup> of scintillators
- ~620 m<sup>2</sup> of silicon sensors
- ~28000 Si modules
- **6M Si channels**, 0.5 cm<sup>2</sup> or 1.1 cm<sup>2</sup> cell size
- Data readout from all layers
- Trigger readout from alternate layers in CE-E and all layers in CE-H
- **~280 kW**

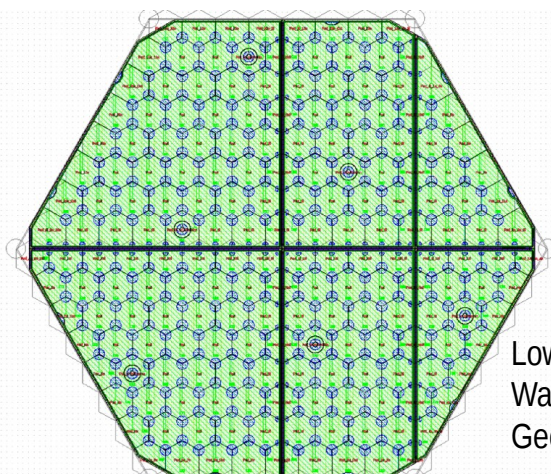


# Cassettes: CE-E (Double Sided)

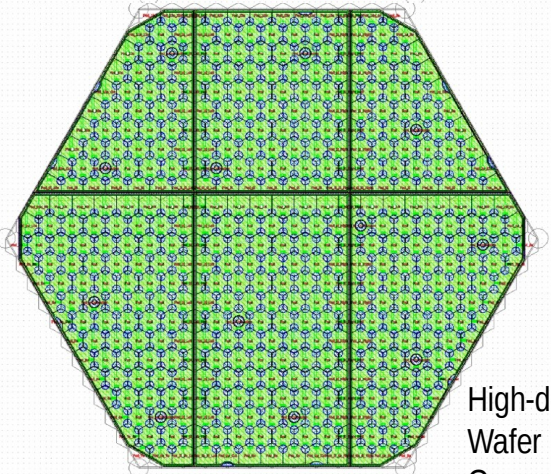
- Layers 1-28
- Silicon-only design
- 6-fold rotational symmetry
- High Density (HD) in inner regions
  - 0.5cm<sup>2</sup> diode pad
- Low Density (LD) in outer regions
  - 1.1cm<sup>2</sup> diode pad
  - Occupancy (=rate) and radiation field determined
- Hexagons optimise silicon wafer usage
  - Significant cost reduction of rectangular (30%)
  - 200 mm wafers used
- Partials at inner/outer perimeters
  - Increases coverage
  - Increases # variants
  - Novel “multi-geometry” wafer



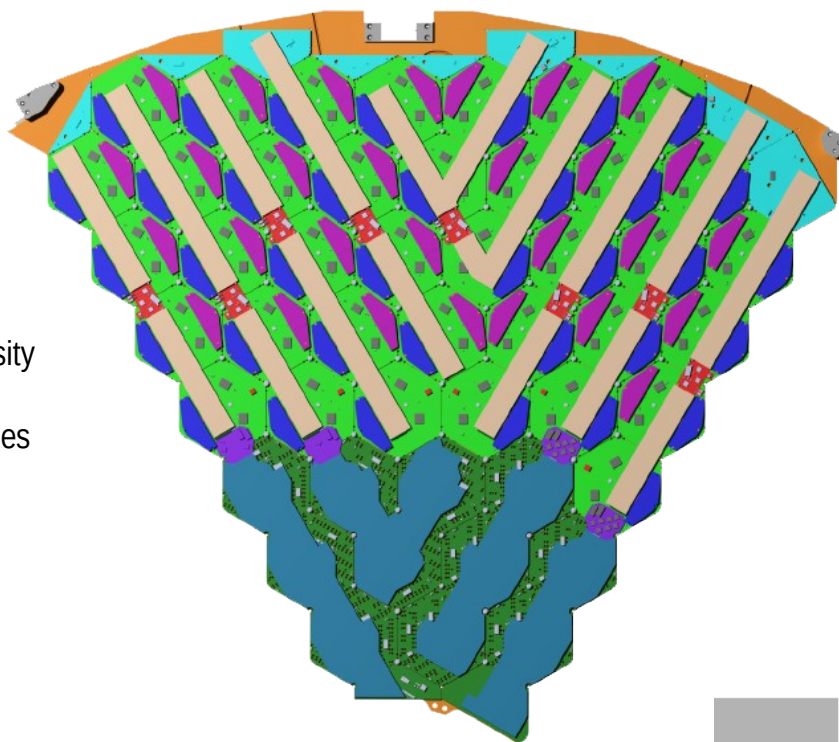
# Coverage, Tiling and Partial Types



Low-density  
Wafer  
Geometries

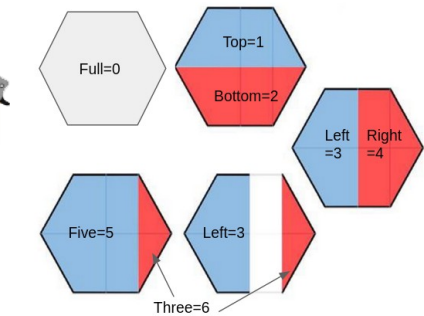


High-density  
Wafer  
Geometries

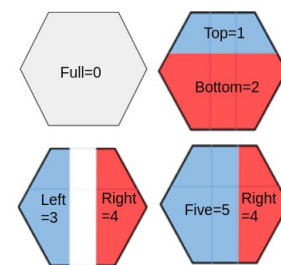


Large number of variants required →  
Significant design task

LD partial sensor layouts



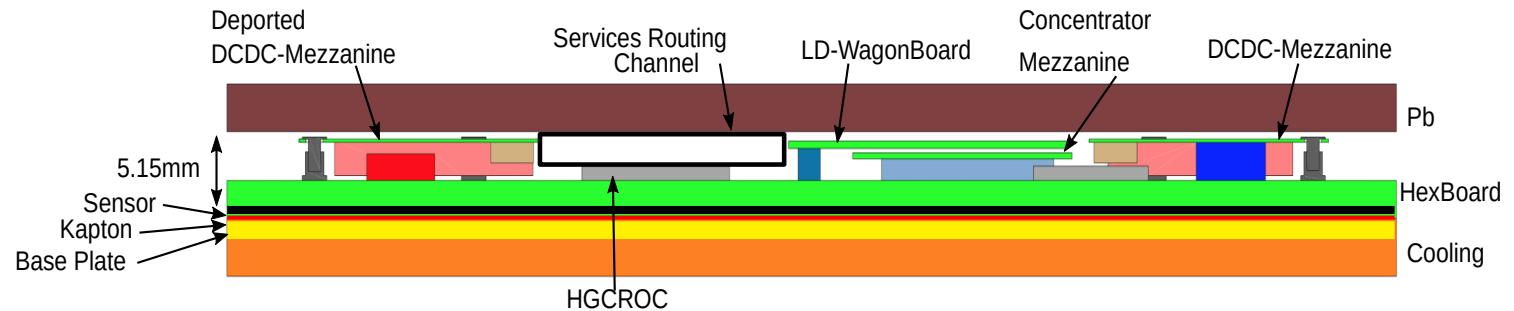
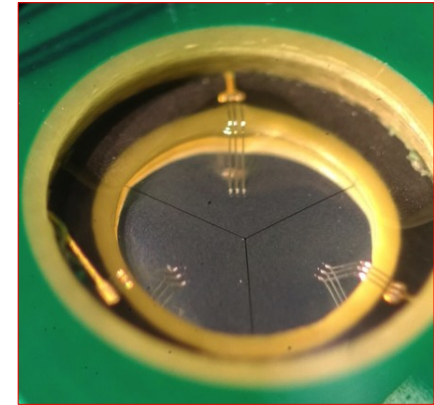
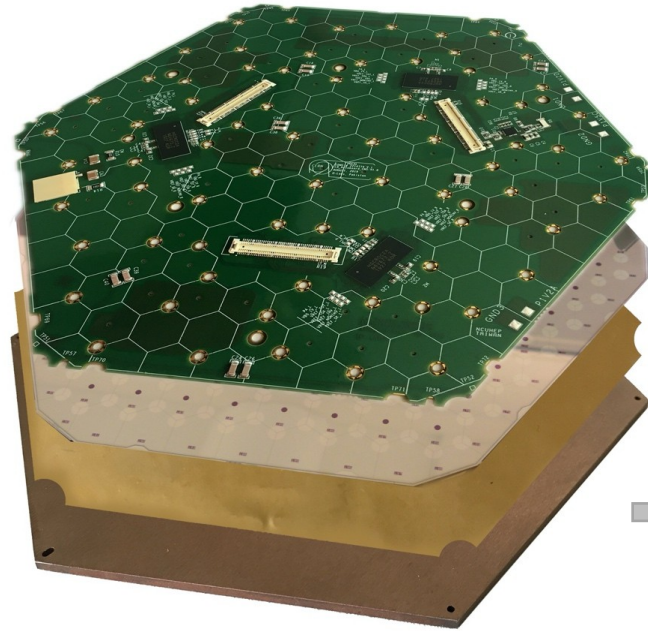
HD partial sensor layouts



	HD		LD		Total
	Full	Partial	Full	Partial	
CE-E	3576	672	10056	2520	16824
CE-H	900	156	8046	2130	11232
Total	4476	828	18102	4650	28056
Fraction	16%	3%	64%	17%	100%

# Vertical Stackup and Space Constraints

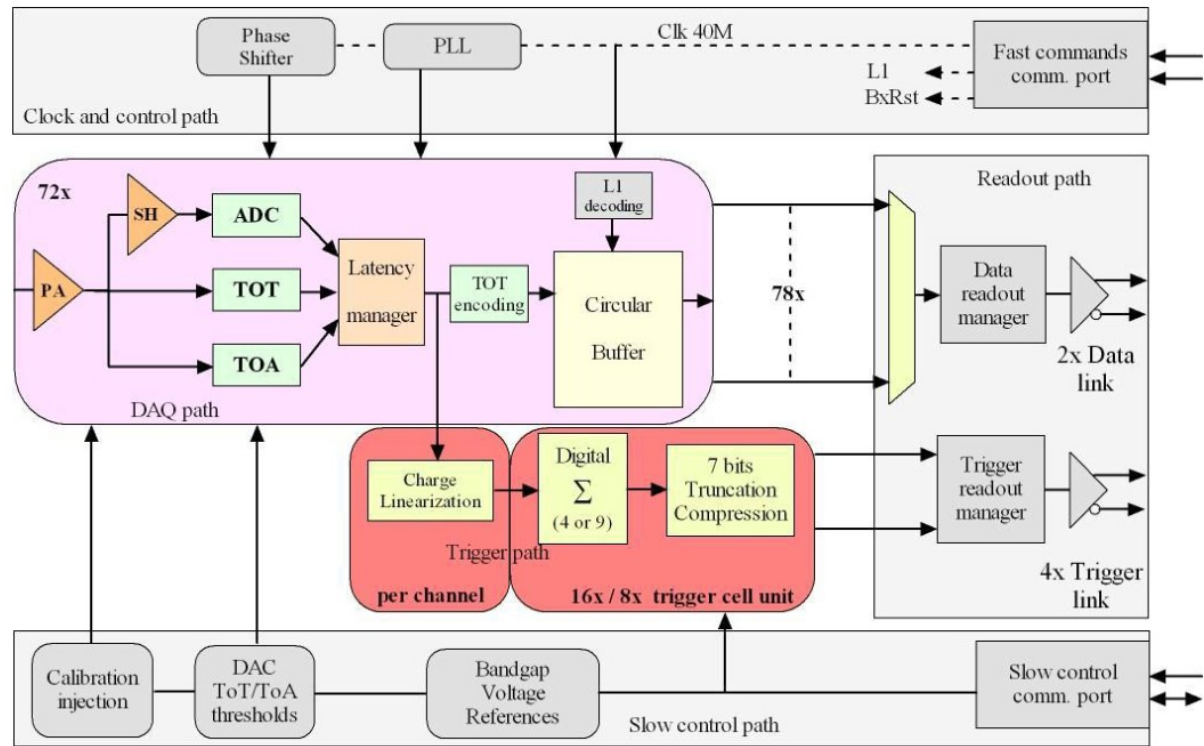
- 5.15mm between Cu & Pb
- Stepped holes
  - Connection through the PCB to sensor
  - Wire bonds used for CTE
  - Swiss cheese
  - Component placement and signal routing is difficult
- Cassette access is radial
  - Power,
  - Triggering, Timing, & Control,
  - Data (DAQ + Trigger)
  - Bias voltage
  - All must pass through outer periphery
- -30°C operation
  - Requires dry environment → pipe



# Main Si Front End Requirements

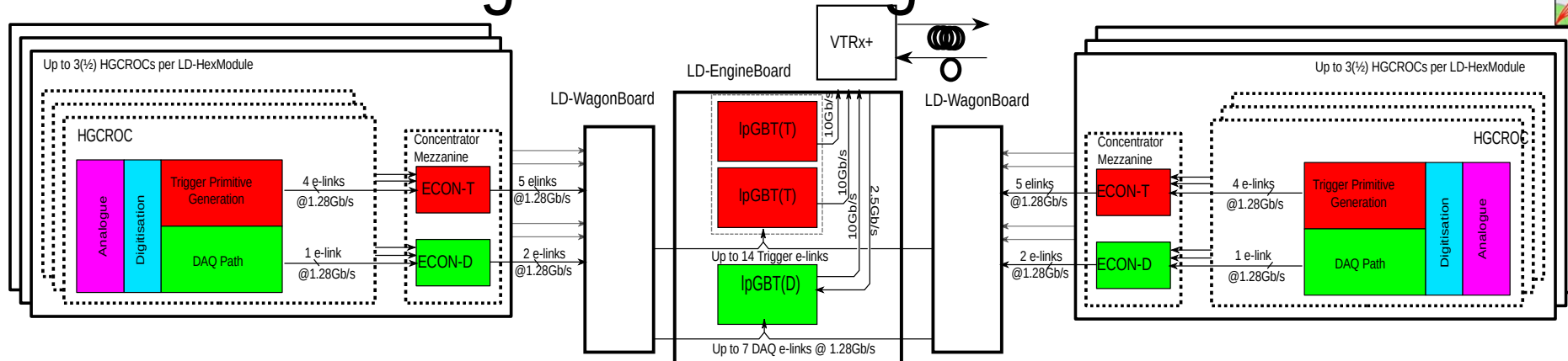


- Dynamic range:
  - $0.2fC \rightarrow 10pC$
- $T_{res} \sim 20ps \rightarrow 30ps$  rms (shower)
- HGCROC deals with these points
  - High Granularity Calorimeter Read-Out Chip
  - See Damien's talk tomorrow
- $\sim 20$  mW/channel
  - Analog + digital
- L1 Trigger Sums (fixed latency)
  - Alternate layers in CE-E
  - All layers in CE-H
- DAQ data zero suppression
  - 750 kHz trigger rate
  - Latency up to  $12.5 \mu s$

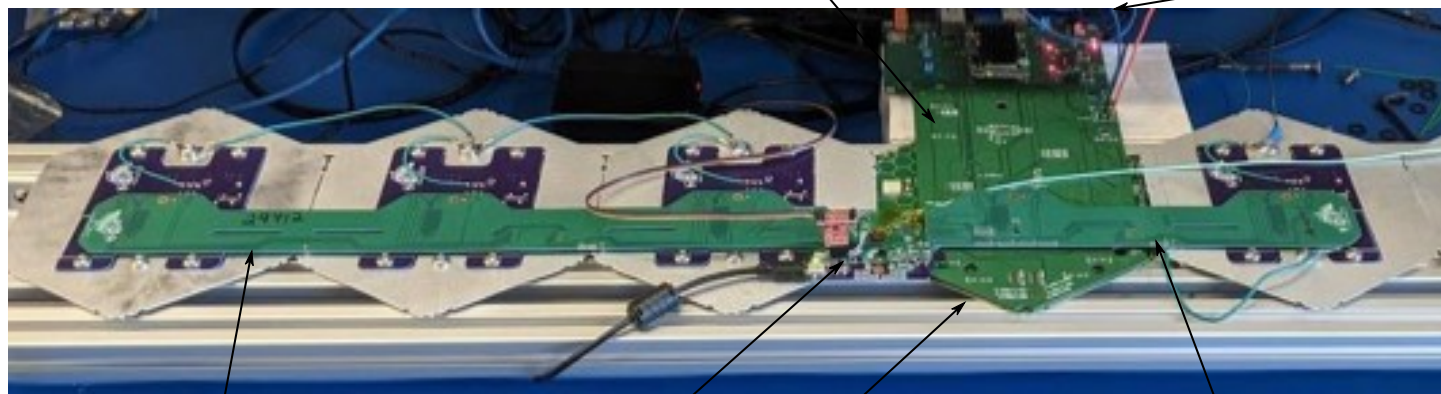




# ReadoutTrain: Engines and Wagons



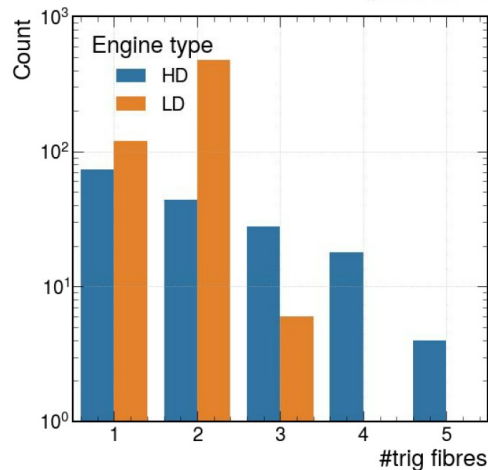
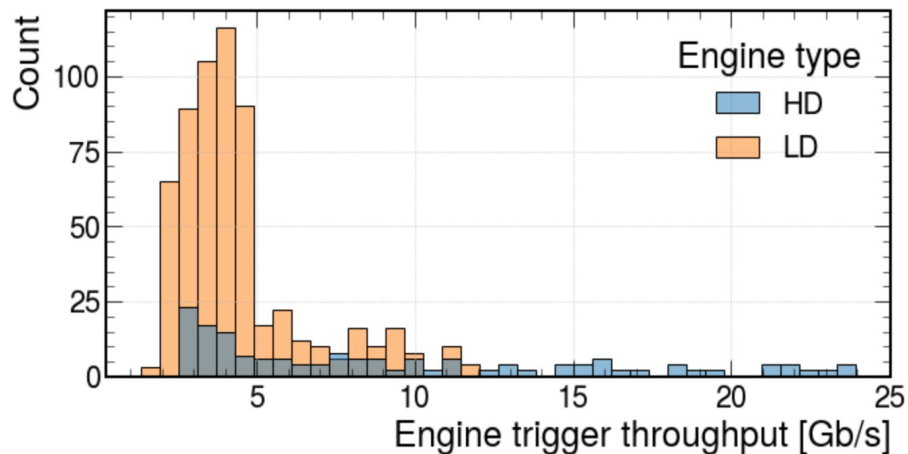
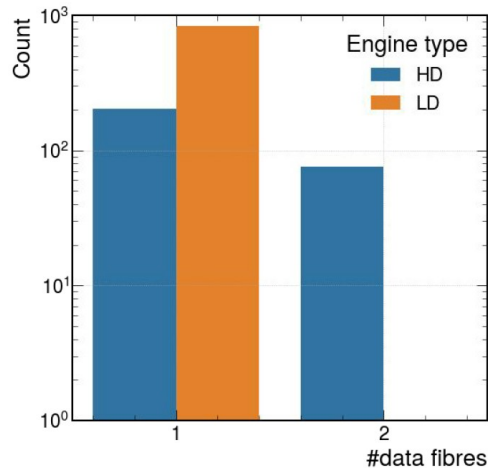
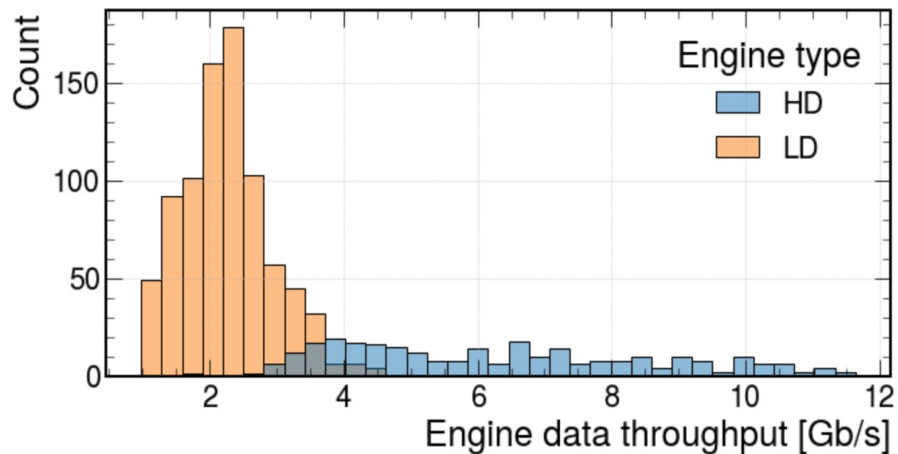
LD-ReadoutTrain Prototype Test System      Wagons      Engine Interposer      Wagons      Controller



LD-WagonBoard      LD-EngineBoard      LD-HexBoard      LD-WagonBoard

- Design is consequence of
  - Large and irregular area
  - Inaccessibility
  - Fine pitch of components
  - Wide range of data rates
  - Space constraints
  - Cost
  - + others

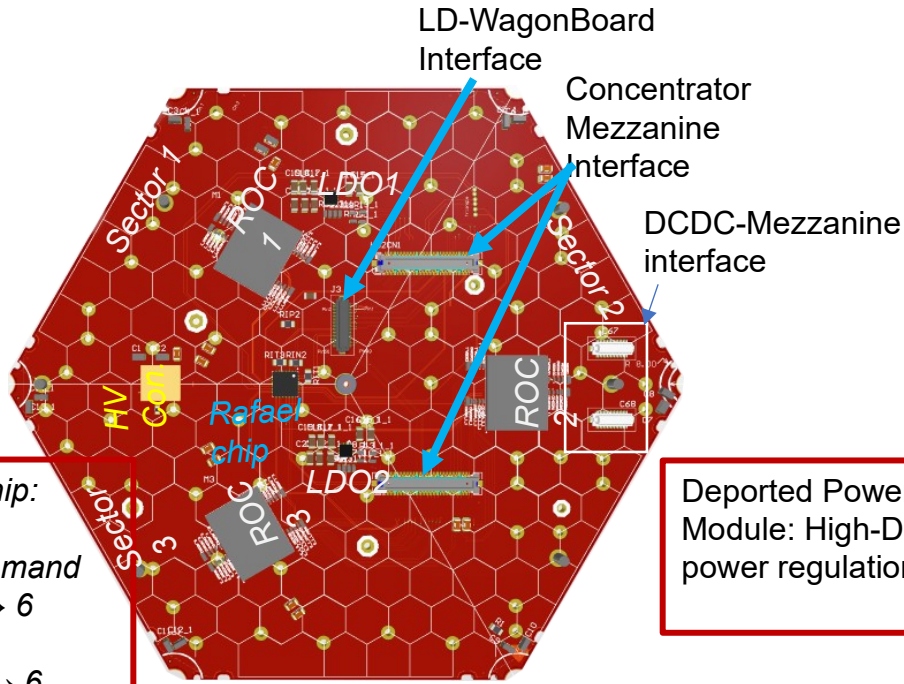
# EngineBoard Data and Trigger-Rate Requirements



- Very high-rate capacity required
- Data links
  - All LD fit in 1x 10Gb/s link
  - 25% of HD require 2
- Trigger
  - A few LD s require 3 links
    - Threshold
  - A few HD s require up to 5 links
- Mapping
  - Detailed matching of bandwidth requirements to fibres essential

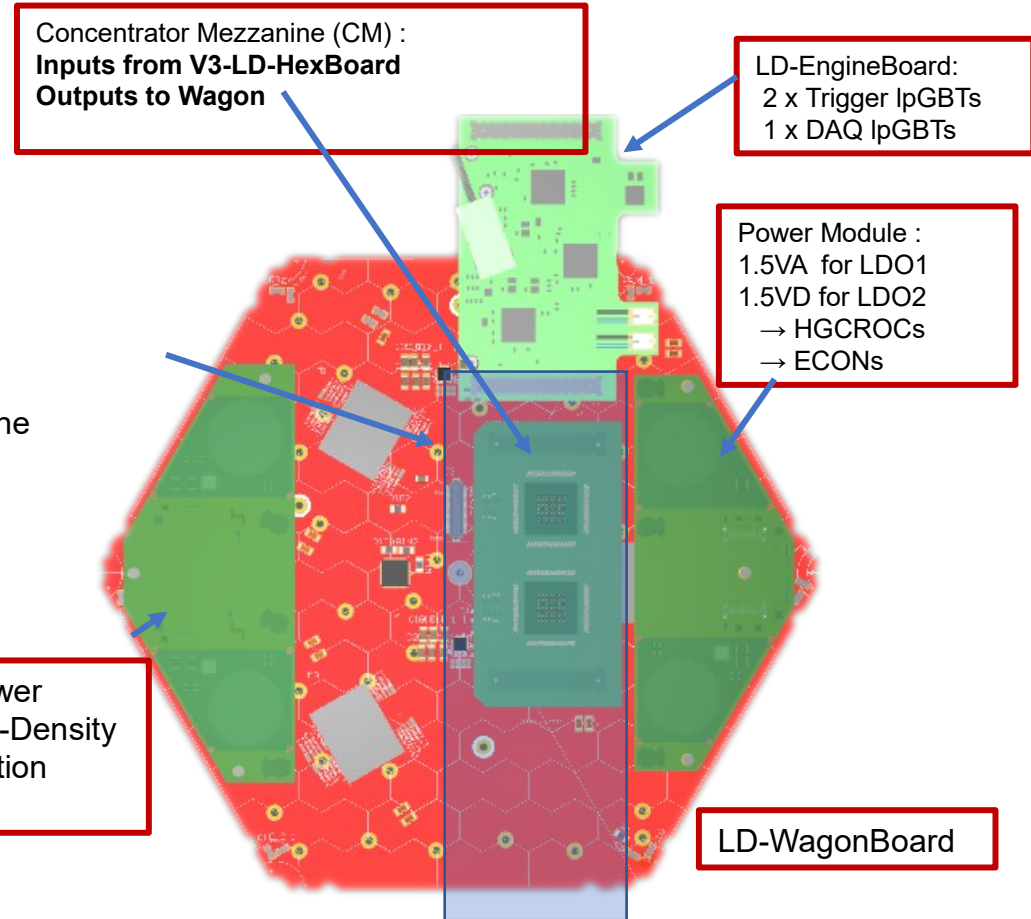
# V3-LD-HexBoard Design

**3 sectors and reads 192 Si channels (64 ch/sector)**  
Hosts 3×HGCROC  
2× LDOs, Rafael Chip, HV connector,  
LD-WagonBoard & DCDC Interfaces

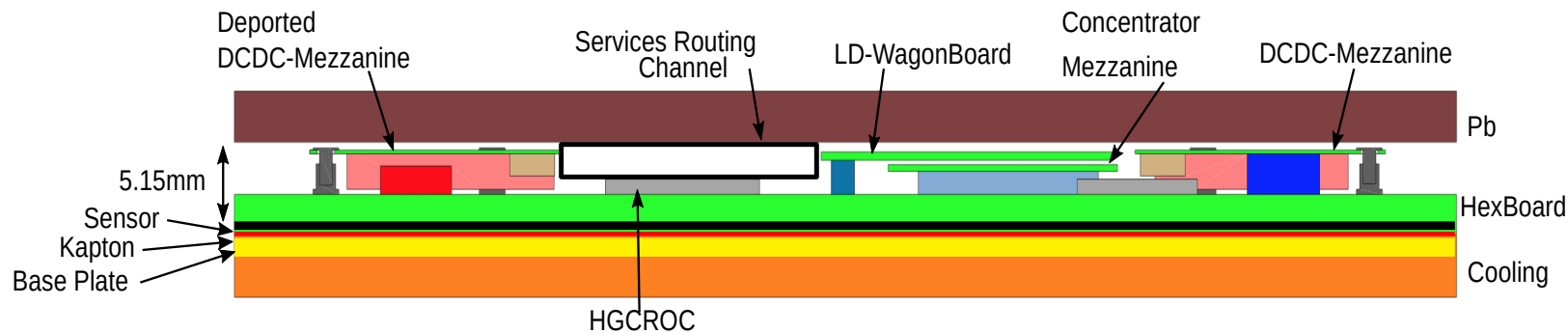
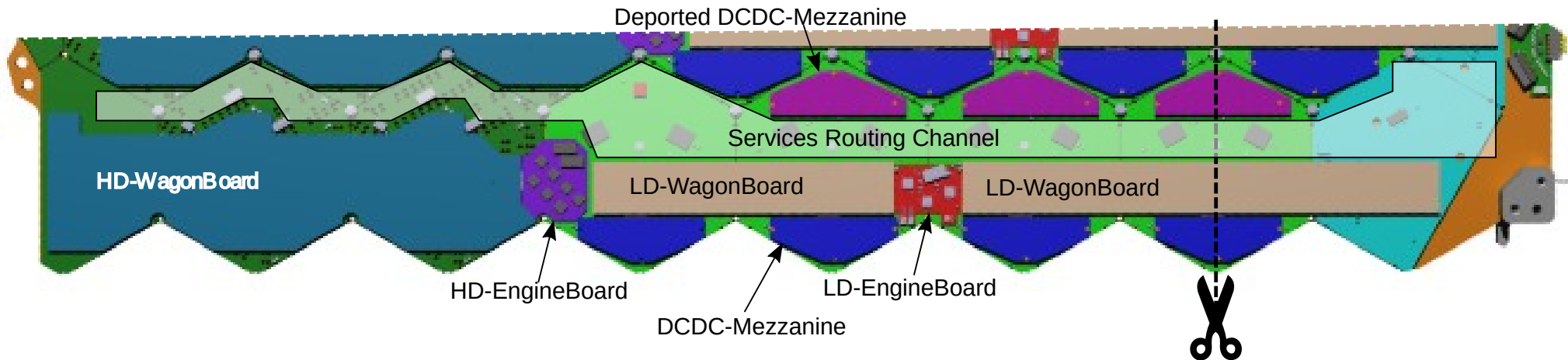


Deported Power Module: High-Density power regulation

## LD-HexModule Assembly



# Services Routing Challenge



# Cassette mockup activity – cassette internal routing

Unavoidable cable crossings

Not enough deported DC/DC in one modules row requires 'stealing' from other rows. This will develop additional cable crossings. Cables have to fit underneath LD wagons

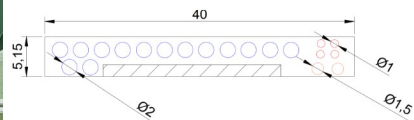
Crossings above HGCROCs

not enough space in height (see cross section drawing)

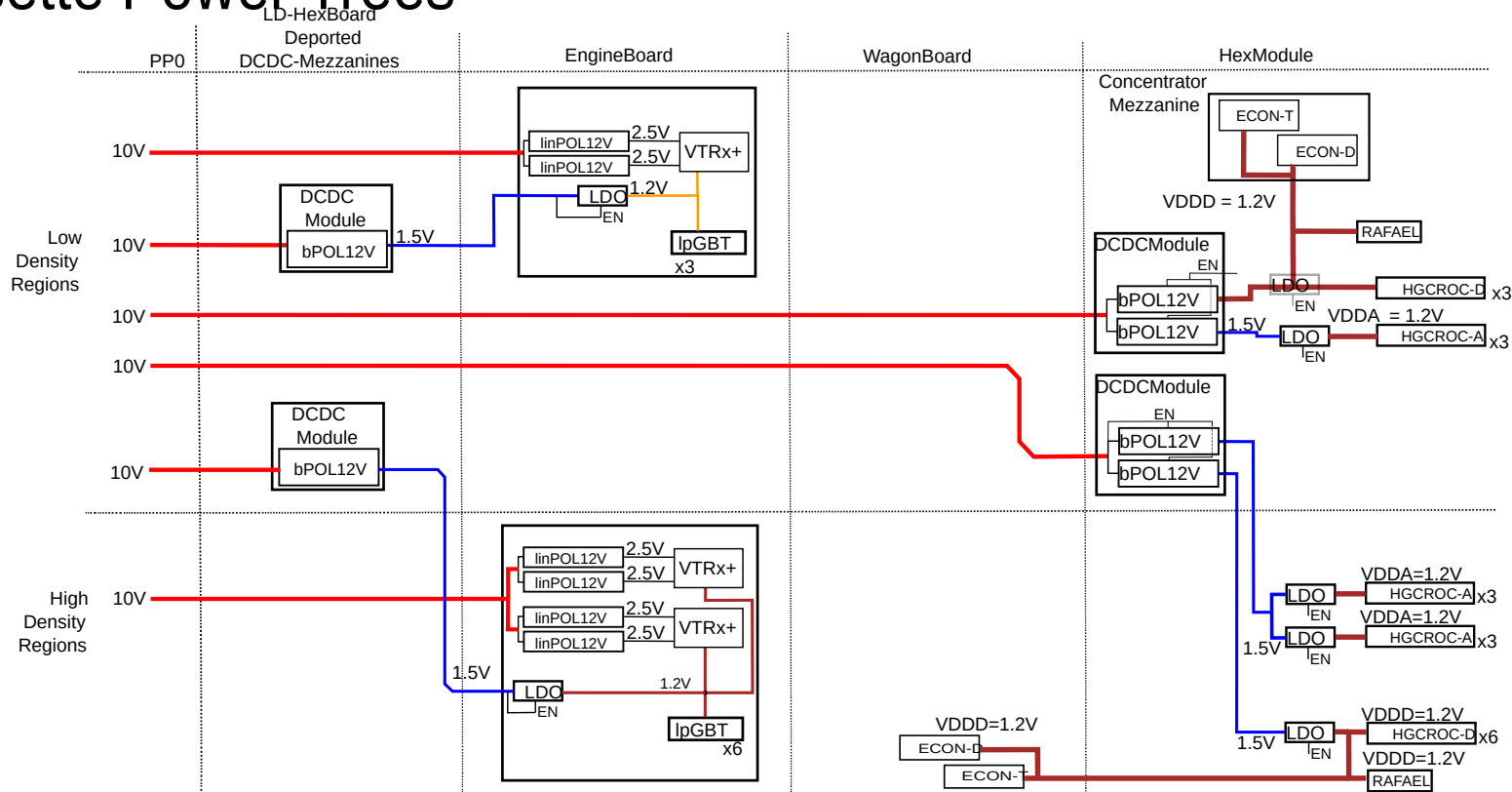
Choke point, not enough space in height. Lack of space for cable supports

To power some of the partials routing cables underneath wagons may be required (is it feasible in that particular place?)

Services routing space occupied with cables (with HGCROC)



# On-Cassette Power Trees



- Common developments where possible
- 10V from outside
  - to go as far as possible into the cassette
  - Routing space

- bPOL12V
- 10V → 1.5V/1.2V
- DCDC-Mezzanine cards
- Custom development
- Careful coil optimisation (shape/space)

- LDO
  - 1.5V → 1.2V
  - Rad hard custom development for HGCA
- linPOL12V
  - 10V → 2.5V
  - Recently adopted to remove bPOL2V5
  - Greatly eases space requirements

# On-Cassette Power Modelling



- Geometry and component based model
  - Power referred to at the cassette periphery
- Active components
  - HGCROC, ECONS, RAFAEL
  - VTRx+, lpGBT..
- Converter losses
- Cable losses
- Allows detailed evaluation of
  - Where power is consumed
  - What the losses are
  - Consequences of cable choices
- Cable dimensioning
  - Supply droop and ground offsets
- Measured power consumptions will improve accuracy

The spreadsheet displays several key tables:

- HexModule Power Summary:** Lists power consumption for various HexModule variants (FI, al, bl, dl, gl, FO, aO, bO, cO, dO, FM, aM, bM) across different power groups.
- Table 39: HGCROC Counts for each HexModule variant:**

Region	HD					LD							
	FI	al	bl	dl	gl	FO	aO	bO	cO	dO	FM	aM	bM
HGCROCs/HM	6	3	4	3	4	3	2	2	1	2	3	2	2
- Power Distribution Tables:** Provide detailed breakdowns of power consumption for different components like HGCROC3-Dig, HGCROC3-Ana, and RAFAEL.

Nominal	HD			LD			
	Type	Full	Partials	Engine	Full	Partials	Engine
Power (W)	14.0	7.6 to 11.5	7.3	6.4	2.1 to 6.4	3.8	
Loss (W)	7.6	3.7 to 6.0	3.9	2.6	1.3 to 2.6	2.1	
Loss (%)	55	50 to 52	53	41	41 to 60	54	

Total Power and losses at PP0 for 2 x 50 layer End-Caps						
	Min		Nom		Max	
	Power	Loss	Power	Loss	Power	Loss
<b>Total (kW)</b>	<b>223.44</b>	<b>110.86</b>	239.86	112.05	257.34	113.04

# Summary and Outlook



- Very demanding system requirements
  - High data rates
  - Tightly constrained physical volume
  - Huge number of channels
  - Optimal coverage introduces a plethora of variations
  - System has a phenomenology that needs to be explored
- Engine-Wagon architecture defined to respond to this complexity
  - Prototype system under evaluation
- Integrated electromechanical design process is required
  - Electronics engineers must work in synergy with the mechanical engineers
- Mechanical mockup developed in conjunction with very detailed modelling and design in use
- Huge design task remaining
  - Every partial needs similar attention to detail



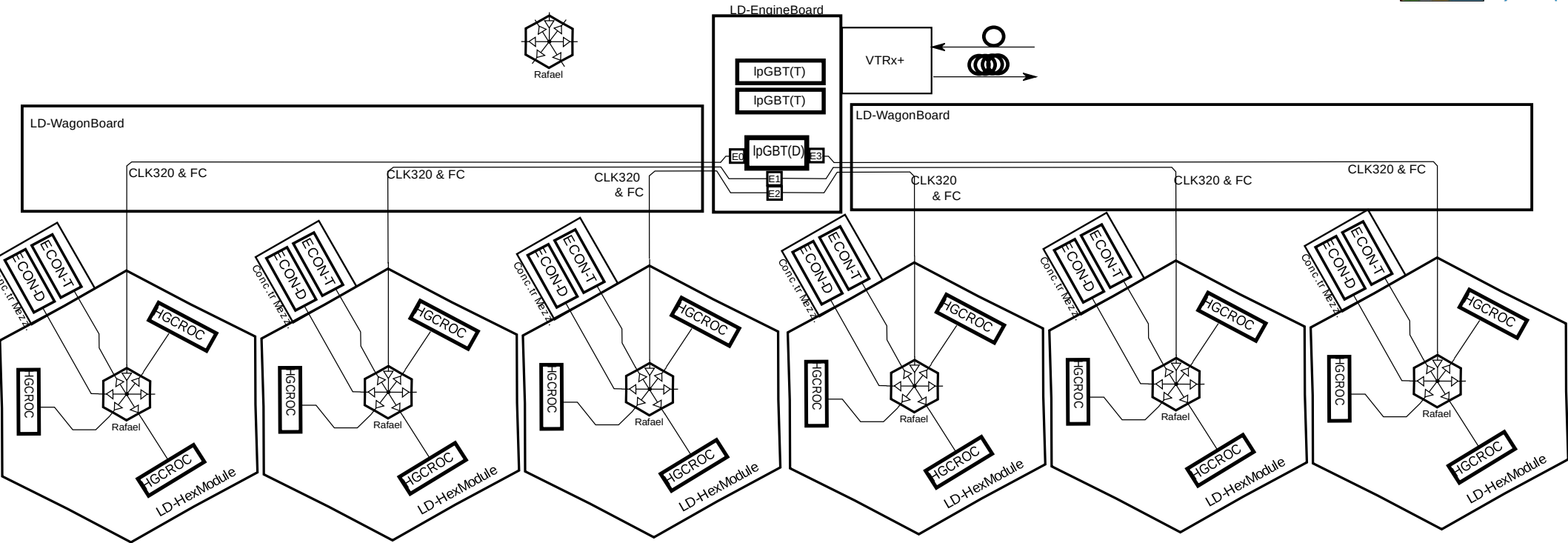
Thank you for your attention!

# Other HGICAL Contributions

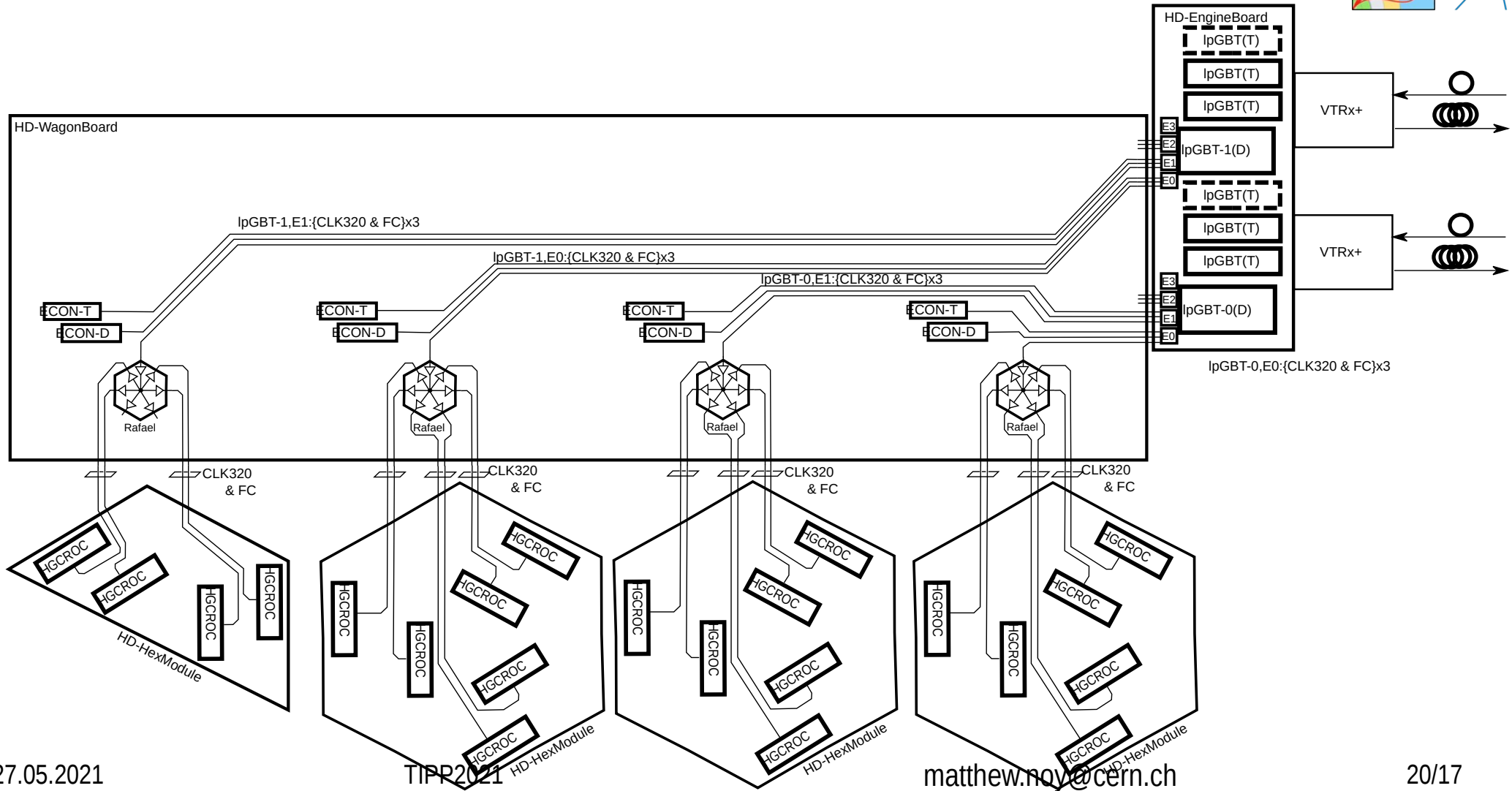


- Clemens Lange: 26.05.2021
  - Beam Tests
  - <https://indi.to/nGjyq>
- Thorben Quast: 26.05.2021
  - Subdetector Overview
  - <https://indi.to/qS3tX>
- Mathias Reinecke: 26.05.2021
  - Scintillator Tileboard
  - <https://indi.to/BY9Qs>
- Damien Thienpont: 28.05.2021
  - HGCROC
  - <https://indi.to/6xk3R>

# Control Architecture: LD Fast Command

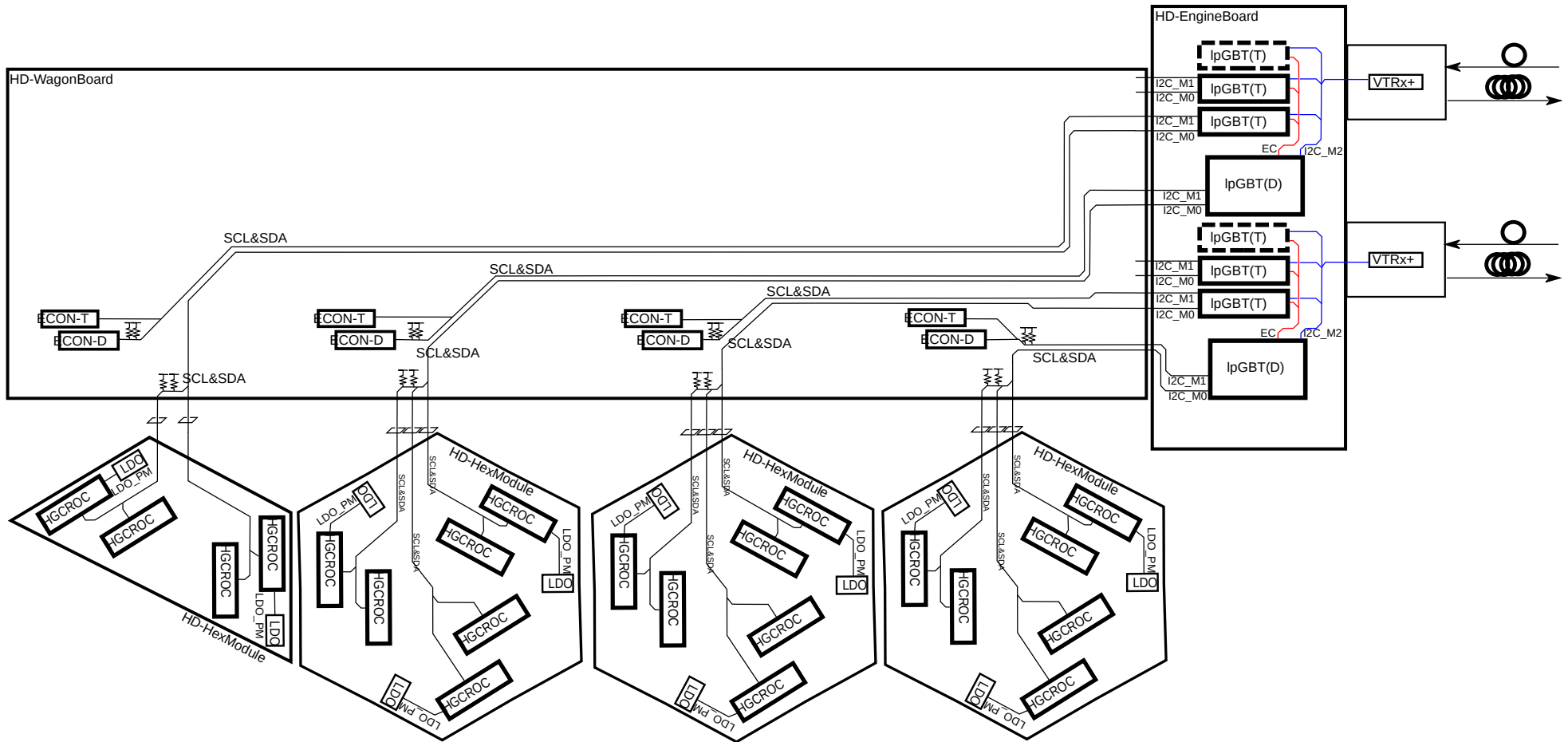


# Control Architecture: HD Fast Command





# HD Slow Control



# Concentrator Mezzanine Card

